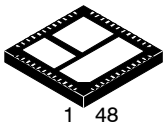
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

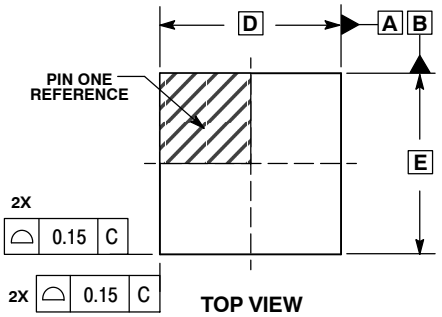
ON Semiconductor®

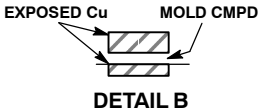
QFN48 6x6, 0.4P
CASE 485CJ
ISSUE A

DATE 09 AUG 2012



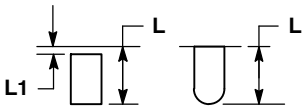
SCALE 2:1



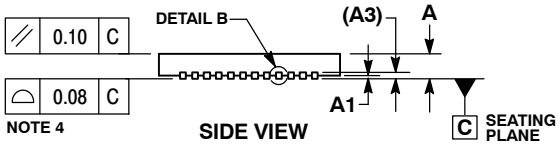


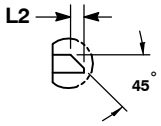
DETAIL B
ALTERNATE CONSTRUCTION

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSIONS: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM TERMINAL TIP
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. POSITIONAL TOLERANCE APPLIES TO ALL THREE EXPOSED PADS IN BOTH X AND Y AXIS.



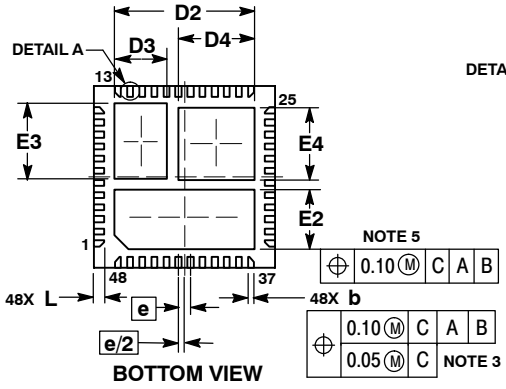
DETAIL A
ALTERNATE TERMINAL CONSTRUCTIONS

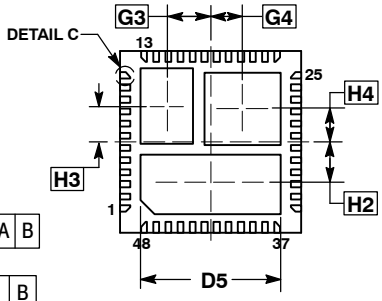




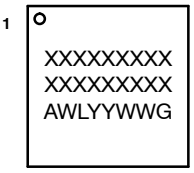
DETAIL C

	MILLIMETERS	
DIM	MIN	MAX
A	0.80	1.00
A1	---	0.05
A3	0.20 REF	
b	0.15	0.25
D	6.00 BSC	
D2	4.53	4.73
D3	1.64	1.84
D4	2.42	2.62
D5	4.58	4.78
E	6.00 BSC	
E2	1.86	2.06
E3	2.41	2.61
E4	2.30	2.50
e	0.40 BSC	
G3	1.45 BSC	
G4	1.06 BSC	
H2	1.40 BSC	
H3	1.19 BSC	
H4	1.10 BSC	
L	0.25	0.45
L1	---	0.15
L2	0.15 REF	





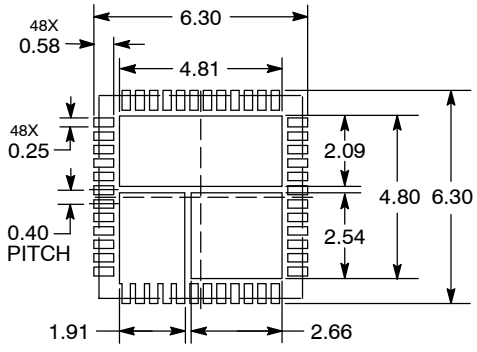
GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot " ▪", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	QFN48, 6x6, 0.4MM PITCH	PAGE 1 OF 2

ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. BY S. MOHAMMED.	24 MAY 2012
A	CORRECTED TABLE LABELS ONLY FOR E2, E3 & E4. REQ. BY S. MOHAMMED.	09 AUG 2012